

CLAIMS

What is claimed is:

1 1. A system level device for battery and integrated circuit chip integration comprising:
2 at least one battery;
3 at least one integrated circuit chip powered by said at least one battery; and
4 a package connected to said at least one battery and said at least one integrated circuit
5 chip.

2 2. The device of claim 1, wherein said package connects to said at least one integrated circuit chip through an interior portion of said package.

3 3. The device of claim 1, wherein said at least one battery overhangs said at least one integrated circuit chip, wherein said at least one integrated circuit chip connects to an upper indent portion of said package, wherein said at least one battery is larger than said at least one integrated circuit chip.

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1 4. The device of claim 1, wherein said at least one battery connects to an underside of said
2 package.

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5. The device of claim 1, wherein said at least one battery connects to a pair of opposed upright ends of said package.

1 6. The device of claim 3, wherein said at least one battery further comprises a stack of
2 connected batteries.

1 7. A system level device for battery and integrated circuit chip integration comprising:
2 a multi-chip module integration system, wherein said multi-chip module integration system
comprises:
3 a multi-chip module;
at least one battery connected to said multi-chip module; and
at least one integrated circuit chip connected to said battery, wherein said
integrated circuit chip is powered by said battery.

1 8. The device of claim 7, wherein said multi-chip module connects to said at least one
2 integrated circuit chip through an interior portion of said multi-chip module.

1 9. The device of claim 7, wherein said at least one battery overhangs said at least one
2 integrated circuit chip, wherein said at least one integrated circuit chip connects to an upper
3 indent portion of said multi-chip module, wherein said at least one battery is larger than said at
4 least one integrated circuit chip.

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1 10. The device of claim 7, wherein said at least one battery connects to a pair of opposed
2 upright ends of said multi-chip module.

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1 11. An integrated chip structure comprising:
2 an integrated circuit chip; and
3 a battery directly connected to said integrated circuit chip.

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1 12. The structure in claim 11, further comprising solder connections between said battery and
2 said integrated circuit chip.

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1 13. The structure in claim 12, wherein said solder connections comprise an electrical
connection between said battery and said integrated circuit chip.

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1 14. The structure in claim 11, further comprising a package surrounding at least one of said
battery and said integrated circuit chip.

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1 15. The structure in claim 12, wherein said battery is directly connected to said package.

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1 16. An integrated chip structure comprising:
a package;
an integrated circuit chip mounted on said package; and

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a battery directly connected to said package and electrically connected to said integrated circuit chip.

1 17. The structure in claim 16, wherein said battery is held adjacent to said integrated circuit
2 chip by said package.

1 18. The structure in claim 16, wherein said package is between said battery and said integrated
2 circuit chip.

15 19. The structure in claim 16, wherein said battery is electrically connected to said integrated
chip through said battery.

15 20. The structure in claim 16, wherein said battery comprises multiple batteries stacked on
said package.